SDAS168B - APRIL 1982 - REVISED JULY 1996

- 3-State Bus Driving Inverting Outputs
- Buffered Control Inputs
- Package Options Include Plastic Small-Outline (DW), Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

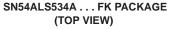
These octal D-type edge-triggered flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively lowimpedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

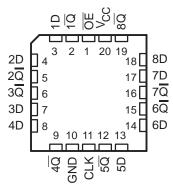
On the positive transition of the clock (CLK) input, the \overline{Q} outputs are set to the complement of the logic states set up at the data (D) inputs. The 'ALS534A and SN74AS534 have inverted outputs, but otherwise are functionally equivalent to the 'ALS374A and SN74AS374.

A buffered output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

SN54ALS534A...J PACKAGE SN74ALS534A, SN74AS534...DW OR N PACKAGE

(TOD VIEW)





OE does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are off.

The SN54ALS534A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS534A and SN74AS534 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)								
	INPUTS		OUTPUT					
OE	CLK	D	Q					
L	\uparrow	Н	L					
L	\uparrow	L	н					
L	H or L	Х						
н	Х	Х	z					



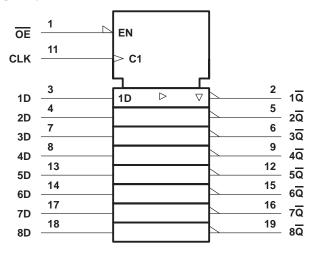
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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



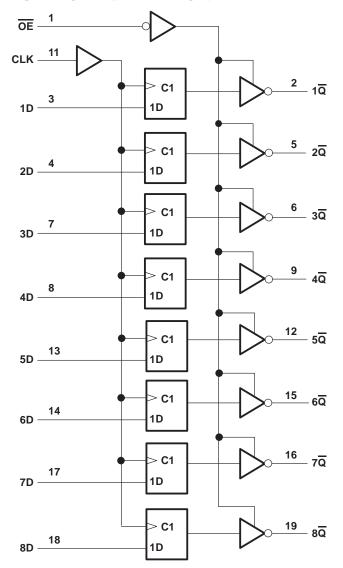
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logic symbol[†]



⁺ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Input voltage, V _I	/V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54ALS534A	-55°C to 125°C
SN74ALS534A	0°C to 70°C
Storage temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	54ALS53	4A	SN7	4ALS53	4A	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-1			-2.6	mA
IOL	Low-level output current			12			24	mA
fclock	Clock frequency	0		30	0		35	MHz
tw	Pulse duration, CLK high or low	16.5			14			ns
t _{su}	Setup time, data before CLK1	10			10			ns
t _h	Hold time, data after CLK↑	0			0			ns
ТА	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST O	TEST CONDITIONS			4A	SN74ALS534A			UNIT	
PARAMETER	TEST C				MAX	MIN	TYP‡	MAX	UNIT	
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.5			-1.5	V	
	V _{CC} = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2			
VOH	V _{CC} = 4.5 V	I _{OH} = -1 mA	2.4	3.3					V	
	VCC = 4.5 V	I _{OH} = -2.6 mA				2.4	3.2			
Ve		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V	
VOL	$V_{CC} = 4.5 V$	I _{OL} = 24 mA					0.35	0.5	v	
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ	
IOZL	V _{CC} = 5.5 V,	$V_{O} = 0.4 V$			-20			-20	μΑ	
lj –	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA	
Ιн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ	
CLK, OE		V ₁ = 0.4 V			-0.1			-0.1	~ ^	
IIL D	$V_{CC} = 5.5 V,$	V] = 0.4 V		-0.2				-0.2	-0.2 mA	
IO§	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA	
		Outputs high		11	19		11	19		
ICC	$V_{CC} = 5.5 V$	Outputs low		19	28		19	28	mA	
		Outputs disabled		10	31		20	31		

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	то (оитрит)	CL R1 R2	c = 4.5 \ = 50 pF, = 500 Ω, = 500 Ω, = MIN to			UNIT
			SN54AL	S534A	SN74AL		
			MIN	MAX	MIN	MAX	
fmax			30		35		MHz
^t PLH	CLK	Am. 0	3	17	3	12	ns
^t PHL	ULK	Any Q	4	18	4	16	115
^t PZH	OE	Am. 0	3	19	3	17	ns
tPZL	UE	Any Q	4	20	4	18	115
^t PHZ	ŌĒ	Any Q	1	12	1	10	200
^t PLZ	UE	Any Q	1	25	2	14	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V	
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN74AS534	0°C to 70°C
Storage temperature rang, T _{stg}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

				SN	174AS53	4	UNIT
				SN74AS534 MIN NOM 4.5 5 2 2 0 4 3 2	MAX	UNIT	
VCC	Supply voltage			4.5	5	5.5	V
VIH	High-level input voltage			2			V
V _{IL}	Low-level input voltage					0.8	V
ЮН	High-level output current				-15	mA	
IOL	Low-level output current					48	mA
fclock	Clock frequency			0		125	MHz
	Pulse duration	CL	.K high	4			
tw	Pulse duration	CL	K low	3			ns
t _{su}	Setup time, data before CLK↑			2			ns
t _h	Hold time, data after CLK↑		2			ns	
TA	Operating free-air temperature		0		70	°C	



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COND	TIONS	SN	74AS53	4	LINUT
PARAMETER	TEST COND	UTIONS	MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lı = – 18 mA			-1.2	V
Veri	$V_{CC} = 4.5 V$ to 5.5 V,	I _{OH} = -2 mA	V _{CC} -2			V
VOH	$V_{CC} = 4.5 V,$	I _{OH} = -15 mA	2.4	3.3		v
V _{OL}	$V_{CC} = 4.5 V,$	I _{OL} = 48 mA		0.34	0.5	V
Іодн	$V_{CC} = 5.5 V,$	V _O = 2.7 V			50	μΑ
IOZL	V _{CC} = 5.5 V,	V _I = 0.4 V			-50	μΑ
lj –	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1	mA
Чн	V _{CC} = 5.5 V,	VI = 2.7 V			20	μΑ
OE, CLK					-0.5	A
IL D	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$			-2	mA
10‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
		Outputs high		77	120	
ICC	V _{CC} = 5.5 V			84	128	mA
		Outputs disabled		84	128	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

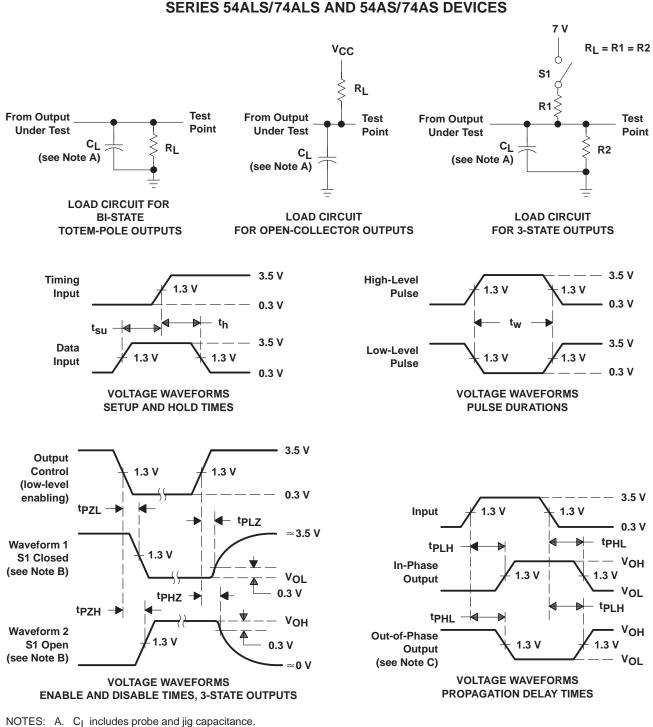
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 C _L = 50 pF R1 = 500 Ω R2 = 500 Ω T _A = MIN tr SN74/	; <u>0,</u> 0, MAX§	UNIT	
			MIN	MAX		
fmax			125		MHz	
^t PLH	CLK	Any Q	3	8	ns	
^t PHL	CER	Any Q	4	9	115	
^t PZH	OE	Am. 0	2	6	ns	
tPZL	0E	Any Q	3	10	113	
^t PHZ	OE	Any Q	2	6		
tPLZ	UE UE		2	6	ns	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



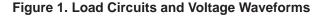
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PARAMETER MEASUREMENT INFORMATION

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_f = t_f = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.





4-Jun-2007

PACKAGING INFORMATION

JMENTS

www ti com

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN54ALS534J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SN74ALS534ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS534ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS534ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS534ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS534ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS534ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS534AN	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS534AN3	OBSOLETE	PDIP	Ν	20		TBD	Call TI	Call TI
SN74ALS534ANE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS534ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS534ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS534ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS534DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74AS534DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74AS534N	OBSOLETE	PDIP	Ν	20		TBD	Call TI	Call TI
SNJ54ALS534FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54ALS534J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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w

(mm)

24.0

Pin1

Quadrant

Q1

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



1	*All dimensions are nominal										
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)
	SN74ALS534ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS534ADWR	SOIC	DW	20	2000	346.0	346.0	41.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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